



MRF486

The RF Line

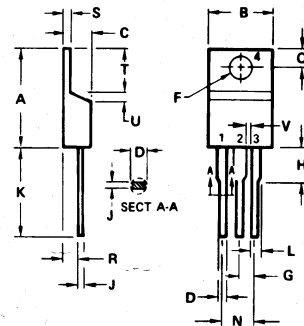
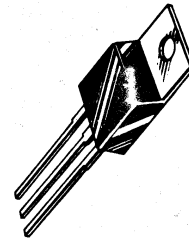
NPN SILICON RF POWER TRANSISTOR

... designed primarily for application as a high-power linear amplifier from 1.5 to 30 MHz, in single sideband mobile, marine and base station equipment.

- Low-Cost, Common-Emitter TO-220 Package
- Specified 28 Volt, 30 MHz Performance –
Output Power = 40 W (PEP)
Power Gain = 15 dB Min
Efficiency = 40% Min
- Intermodulation Distortion @ 40 W (PEP) –
IMD = -30 dB (Max)
- 30:1 VSWR Load Mismatch Capability at Rated Output Power and Supply Voltage

40 W (PEP) – 30 MHz

RF POWER TRANSISTOR
NPN SILICON



STYLE 2:
PIN 1. BASE
2. EMITTER
3. COLLECTOR
4. EMITTER

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	15.11	15.75	0.595	0.620
B	9.65	10.29	0.380	0.405
C	4.06	4.82	0.160	0.190
D	0.65	0.89	0.025	0.035
F	3.61	3.73	0.142	0.147
G	2.41	2.67	0.095	0.105
H	2.79	3.30	0.110	0.130
J	0.36	0.56	0.014	0.022
K	12.70	14.27	0.500	0.562
L	1.14	1.27	0.045	0.050
N	4.83	5.33	0.190	0.210
Q	2.54	3.04	0.100	0.120
R	2.04	2.79	0.080	0.110
S	1.14	1.39	0.045	0.055
T	5.97	6.48	0.235	0.255
U	0.76	1.27	0.030	0.050
V	1.14	-	0.045	-

CASE 221A-02
TO-220AB

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	35	Vdc
Collector-Base Voltage	V_{CBO}	65	Vdc
Emitter-Base Voltage	V_{EBO}	4.0	Vdc
Collector Current – Continuous	I_C	3.0	Adc
Withstand Current ($t = 5.0$ s)	–	6.0	Adc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ (1) Derate above 25°C	P_D	87.5 0.5	Watts W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.0	$^\circ\text{C}/\text{W}$

(1) These devices are designed for RF operation. The total device dissipation rating applies only when the devices are operated as RF amplifiers.

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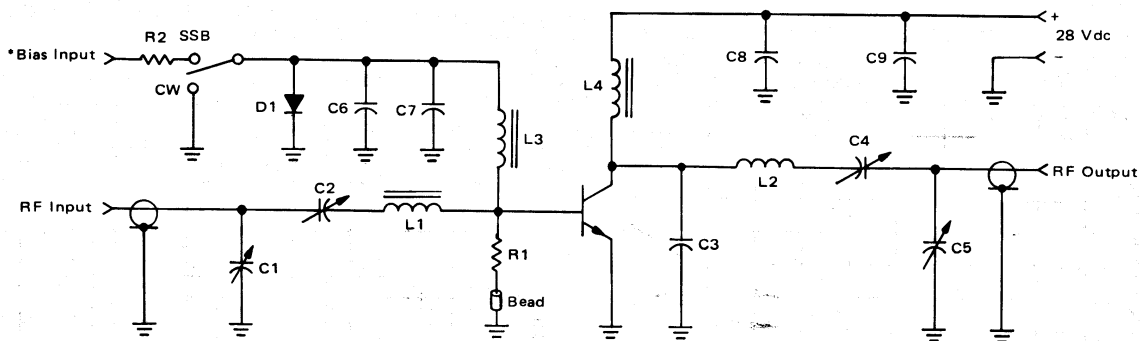
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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage ($I_C = 50 \text{ mAdc}$, $I_B = 0$)	BV_{CEO}	35	—	—	Vdc
Collector-Emitter Breakdown Voltage ($I_C = 50 \text{ mAdc}$, $V_{BE} = 0$)	BV_{CES}	65	—	—	Vdc
Collector-Base Breakdown Voltage ($I_C = 50 \text{ mAdc}$, $I_E = 0$)	BV_{CBO}	65	—	—	Vdc
Emitter-Base Breakdown Voltage ($I_E = 5.0 \text{ mAdc}$, $I_C = 0$)	BV_{EBO}	4.0	—	—	Vdc
Collector Cutoff Current ($V_{CE} = 28 \text{ Vdc}$, $V_{BE} = 0$, $T_C = 25^\circ\text{C}$)	I_{CES}	—	—	10	mAdc
ON CHARACTERISTICS					
DC Current Gain ($I_C = 2.0 \text{ Adc}$, $V_{CE} = 5.0 \text{ Vdc}$)	h_{FE}	10	40	—	—
DYNAMIC CHARACTERISTICS					
Output Capacitance ($V_{CB} = 27 \text{ Vdc}$, $I_E = 0$, $f = 1.0 \text{ MHz}$)	C_{ob}	—	130	200	pF
FUNCTIONAL TESTS					
Common-Emitter Amplifier Power Gain ($V_{CC} = 28 \text{ Vdc}$, $P_{out} = 40 \text{ W (PEP)}$, $f_1 = 30 \text{ MHz}$, $f_2 = 30.001 \text{ MHz}$, $I_{CQ} = 40 \text{ mAdc}$)	G_{PE}	15	17.5	—	dB
Collector Efficiency ($V_{CC} = 28 \text{ Vdc}$, $P_{out} = 40 \text{ W (PEP)}$, $f_1 = 30 \text{ MHz}$, $f_2 = 30.001 \text{ MHz}$, $I_{CQ} = 40 \text{ mAdc}$)	η	40	45	—	%
Intermodulation Distortion (1) ($V_{CC} = 28 \text{ Vdc}$, $P_{out} = 40 \text{ W (PEP)}$, $f_1 = 30 \text{ MHz}$, $f_2 = 30.001 \text{ MHz}$, $I_{CQ} = 40 \text{ mAdc}$)	$IMD(d_3)$	—	-35	-30	dB

(1) To MIL-STD-1311 Version A, Test Method 2204B, Two Tone, Reference Each Tone.

FIGURE 1 — 30 MHz TEST CIRCUIT



C1, C2 — Arco 469, 190–780 pF
 C3 — 150 pF ELMENCO**
 C4, C5 — Arco 429, 90–400 pF
 C6, C9 — 0.001 μF Disc Ceramics
 C7 — 500 μF , 3 Vdc Electrolytic
 C8 — 50 μF , 50 Vdc Electrolytic

R1 — 10 Ω , 1.0 Watt Resistor
 R2 — 5 Ω , 5.0 Watt Resistor
 L1 — 0.15 μH Molded Choke
 L2 — 7 Turns, #16 AWG Enameled Close-Wound, 1/2" ID
 L3 — 10 μH Molded Choke
 L4 — 1.9 μH Molded Choke
 One Bead — #56-590-65/3B (Ferroxcube or equiv.)
 D1 — 1N4997

* Adjust Bias (Base) Voltage for $I_{CQ} = 40 \text{ mA}$ with no RF applied.
 ** Type MCM01/010 or UNELCO 3 HS 0006.

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FIGURE 2 – OUTPUT POWER versus INPUT POWER

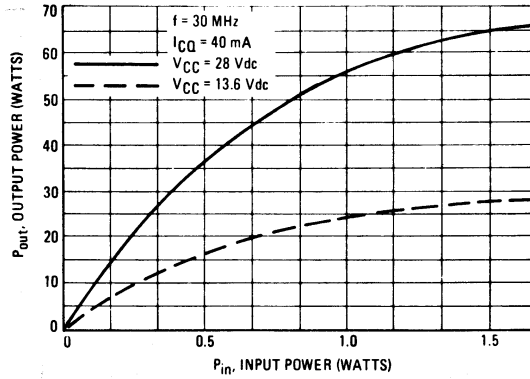


FIGURE 3 – OUTPUT POWER versus SUPPLY VOLTAGE

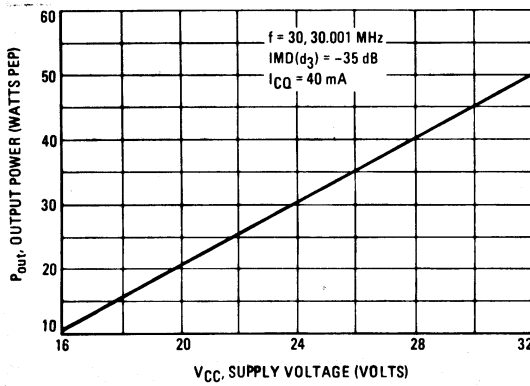


FIGURE 4 – POWER GAIN versus FREQUENCY

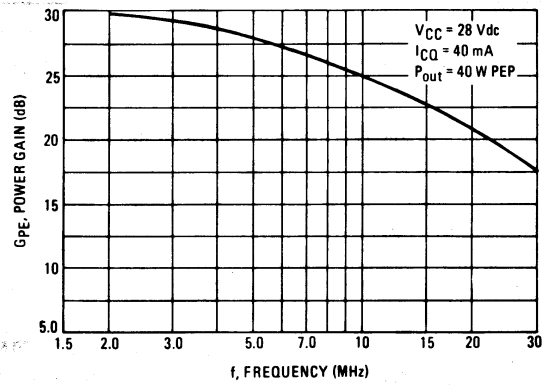


FIGURE 5 – INTERMODULATION DISTORTION versus OUTPUT POWER

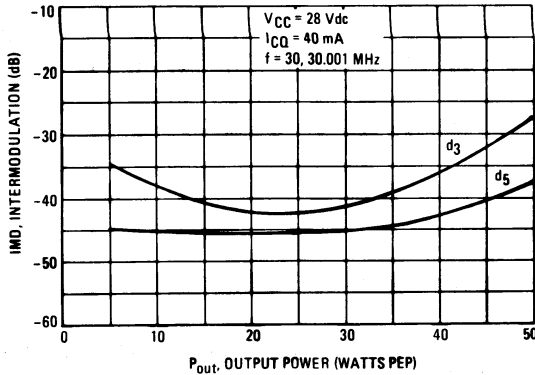


FIGURE 6 – SAFE OPERATING AREA

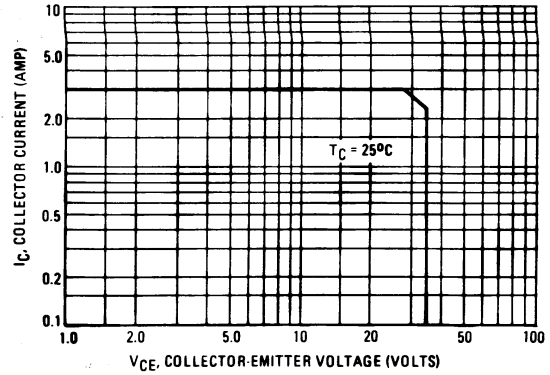


FIGURE 7 - SERIES EQUIVALENT INPUT IMPEDANCE

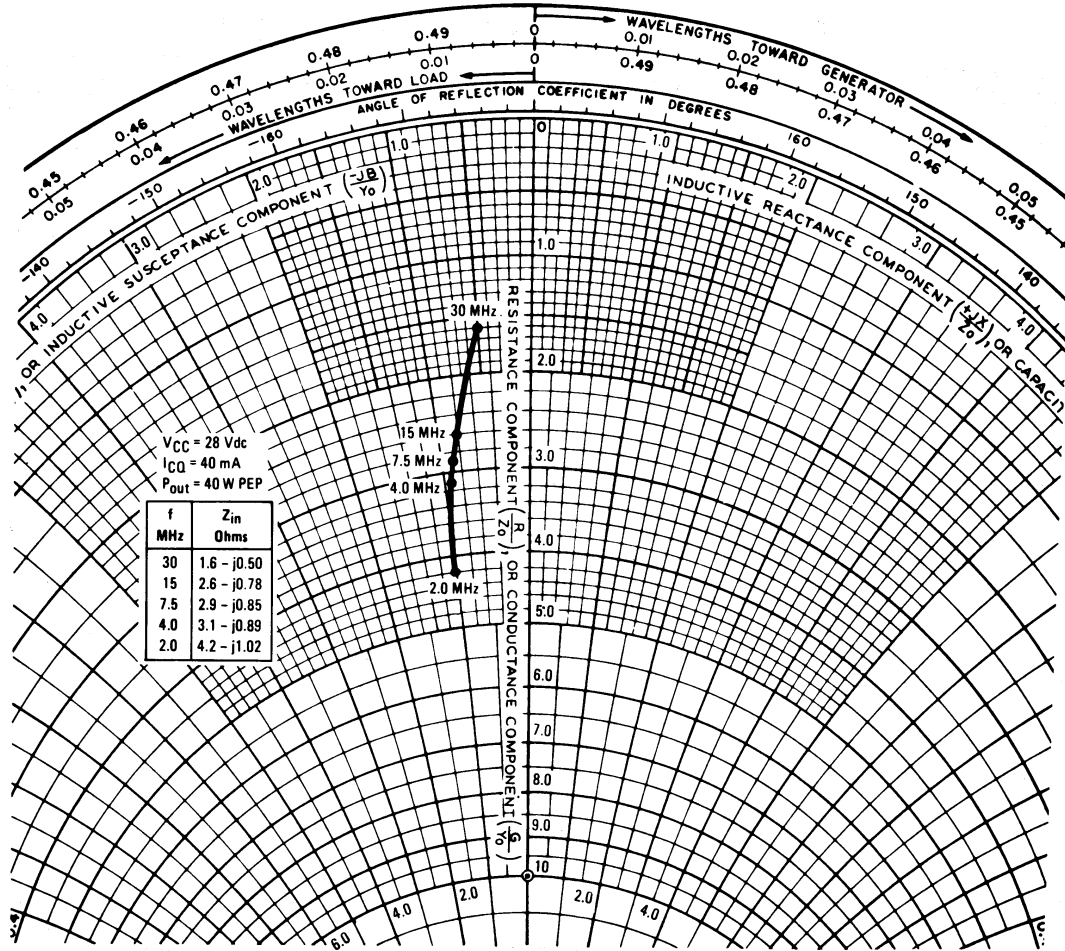


FIGURE 8 - OUTPUT CAPACITANCE versus FREQUENCY

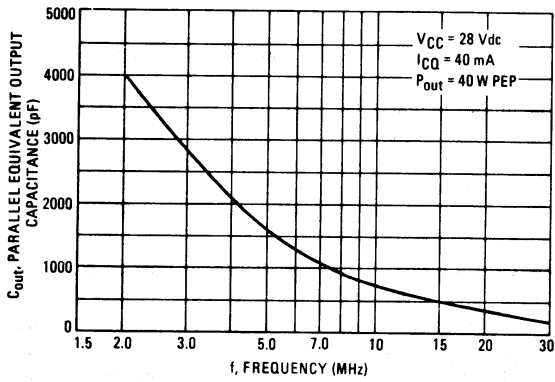


FIGURE 9 - OUTPUT RESISTANCE versus FREQUENCY

